

NL17SG08

Single 2-Input AND Gate

The NL17SG08 MiniGate™ is an advanced high-speed CMOS 2-input AND gate in ultra-small footprint.

The NL17SG08 input structures provides protection when voltages up to 4.6 V are applied.

Features

- Wide Operating V_{CC} Range: 0.9 V to 3.6 V
- High Speed: $t_{PD} = 2.5$ ns (Typ) at $V_{CC} = 3.0$ V, $C_L = 15$ pF
- Low Power Dissipation: $I_{CC} = 0.5$ μ A (Max) at $T_A = 25^\circ$ C
- 4.6 V Overvoltage Tolerant (OVT) Input Pins
- Ultra-Small Packages
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free and Halide-Free Devices

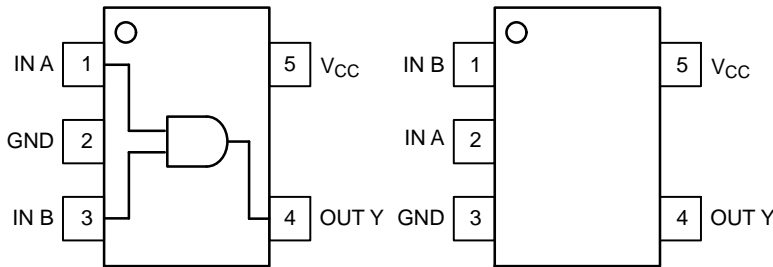


Figure 1. SOT-953
(Top Thru View)

Figure 1. SC-88A
(Top View)

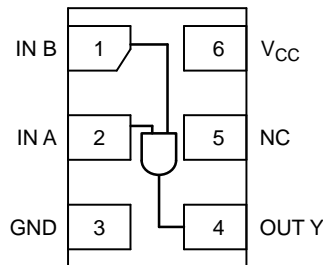


Figure 1. UDFN6
(Top View)

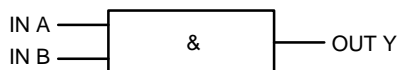


Figure 2. Logic Symbol



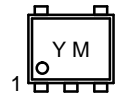
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MARKING DIAGRAMS



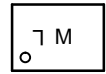
SOT-953
CASE 527AE



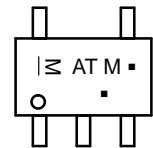
UDFN6
1.0 x 1.0
CASE 517BX



UDFN6
1.45 x 1.0
CASE 517AQ



SC-88A
DF SUFFIX
CASE 419A



M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

PIN	SOT-953	SC-88A	UDFN6
1	IN A	IN B	IN B
2	GND	IN A	IN A
3	IN B	GND	GND
4	OUT Y	OUT Y	OUT Y
5	V_{CC}	V_{CC}	VC
6	-	-	V_{CC}

FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NL17SG08

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +5.5	V
V _{IN}	DC Input Voltage	-0.5 to +4.6	V
V _{OUT}	DC Output Voltage Output at High or Low State Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} +0.5 -0.5 to +4.6	V
I _{IK}	DC Input Diode Current V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current V _{OUT} < GND	-20	mA
I _{OUT}	DC Output Source/Sink Current	±20	mA
I _{CC}	DC Supply Current per Supply Pin	±20	mA
I _{GND}	DC Ground Current per Ground Pin	±20	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature Under Bias	+150	°C
MSL	Moisture Sensitivity	Level 1	
FR	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3)	>2000 >100	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	0.9	3.6	V
V _{IN}	Digital Input Voltage	0.0	3.6	V
V _{OUT}	Output Voltage Output at High or Low State Power-Down Mode (V _{CC} = 0 V)	0.0 0.0	V _{CC} 3.6	V
T _A	Operating Temperature Range	-55	+125	°C
Δt / ΔV	Input Transition Rise or Fall Rate V _{CC} = 3.3 V ± 0.3 V	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NL17SG08

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C		T _A = -55°C to +125°C		Unit
				Min	Max	Min	Max	
V _{IH}	High-Level Input Voltage		0.9	V _{CC}		V _{CC}		V
			1.1 to 1.3	0.7xV _{CC}		0.7xV _{CC}		
			1.4 to 1.6	0.65xV _{CC}		0.65xV _{CC}		
			1.65 to 1.95	0.65xV _{CC}		0.65xV _{CC}		
			2.3 to 2.7	1.7		1.7		
			3.0 to 3.6	2.0		2.0		
V _{IL}	Low-Level Input Voltage		0.9		GND		GND	V
			1.1 to 1.3		0.3xV _{CC}		0.3xV _{CC}	
			1.4 to 1.6		0.35xV _{CC}		0.35xV _{CC}	
			1.65 to 1.95		0.35xV _{CC}		0.35xV _{CC}	
			2.3 to 2.7		0.7		0.7	
			3.0 to 3.6		0.8		0.8	
V _{OH}	High-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	0.9	0.75		0.75	V
			I _{OH} = -0.3 mA	1.1 to 1.3	0.75xV _{CC}		0.75xV _{CC}	
			I _{OH} = -1.7 mA	1.4 to 1.6	0.75xV _{CC}		0.75xV _{CC}	
			I _{OH} = -3.0 mA	1.65 to 1.95	V _{CC} -0.45		V _{CC} -0.45	
			I _{OH} = -4.0 mA	2.3 to 2.7	2.0		2.0	
			I _{OH} = -8.0 mA	3.0 to 3.6	2.48		2.48	
V _{OL}	Low-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	0.9		0.1	0.1	V
			I _{OL} = 1.1 mA	1.1 to 1.3		0.25xV _{CC}	0.25xV _{CC}	
			I _{OL} = 1.7 mA	1.4 to 1.6		0.25xV _{CC}	0.25xV _{CC}	
			I _{OL} = 3.0 mA	1.65 to 1.95		0.45	0.45	
			I _{OL} = 4.0 mA	2.3 to 2.7		0.4	0.4	
			I _{OL} = 8.0 mA	3.0 to 3.6		0.4	0.4	
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 3.6 V	0 to 3.6		±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	3.6		0.5		10.0	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NL17SG08

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ ns)

Symbol	Parameter	Test Condition	V_{CC} (V)	$T_A = 25^\circ\text{C}$			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	
t_{PLH} , t_{PHL}	Propagation Delay, A or B to Y	$C_L = 10$ pF, $R_L = 1$ M Ω	0.9	-	10.0	12.4	-	14.8	ns
			1.1 to 1.3	-	8.0	10.7	-	13.6	
			1.4 to 1.6	-	5.9	9.6	-	11.3	
			1.65 to 1.95	-	4.5	7.0	-	7.5	
			2.3 to 2.7	-	2.9	4.4	-	4.9	
			3.0 to 3.6	-	2.2	3.5	-	4.1	
		$C_L = 15$ pF, $R_L = 1$ M Ω	0.9	-	11.7	13.5	-	15.0	ns
			1.1 to 1.3	-	8.8	10.2	-	13.7	
			1.4 to 1.6	-	6.5	9.5	-	12.6	
			1.65 to 1.95	-	5.0	7.7	-	8.0	
			2.3 to 2.7	-	3.2	4.9	-	5.6	
			3.0 to 3.6	-	2.5	3.8	-	4.4	
		$C_L = 30$ pF, $R_L = 1$ M Ω	0.9	-	13.0	16.0	-	19.0	ns
			1.1 to 1.3	-	10.0	12.4	-	17.2	
			1.4 to 1.6	-	8.9	11.8	-	14.9	
			1.65 to 1.95	-	6.9	10.3	-	10.8	
			2.3 to 2.7	-	4.4	6.4	-	6.8	
			3.0 to 3.6	-	3.5	4.9	-	5.4	
C_{IN}	Input Capacitance		0 to 3.6		3	-	-	pF	
C_{PD}	Power Dissipation Capacitance (Note 4)	$f = 10$ MHz	0.9 to 3.6	-	4	-	-	pF	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

NL17SG08

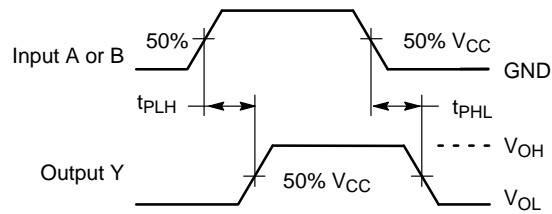
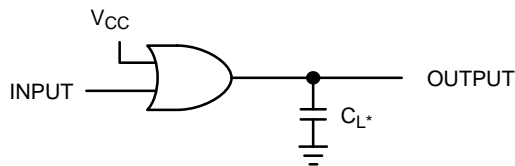


Figure 2. Switching Waveforms



*Includes all probe and jig capacitance.
A 1-MHz square input wave is recommended for propagation delay tests.

Figure 3. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping†
NL17SG08P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel
NL17SG08DFT2G	SC-88A (Pb-Free)	3000 / Tape & Reel
NLV17SG08DFT2G*	SC-88A (Pb-Free)	3000 / Tape & Reel
NL17SG08AMUTCG	UDFN6 1.45x1 mm (Pb-Free)	3000 / Tape & Reel
NL17SG08CMUTCG	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

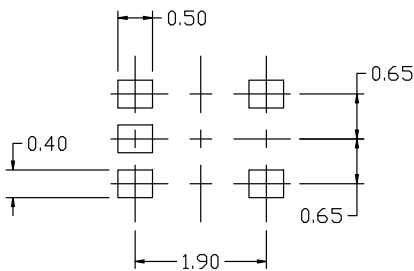
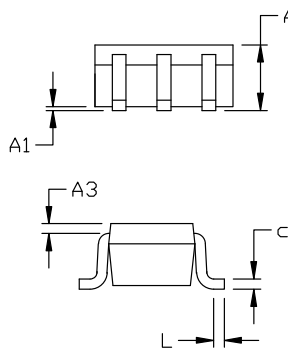
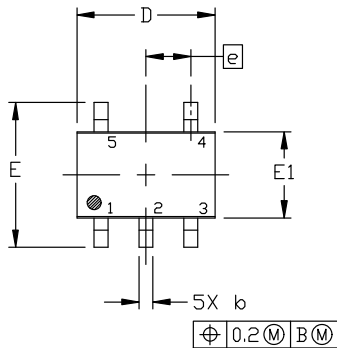
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 2:1

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

DATE 11 APR 2023



RECOMMENDED
MOUNTING FOOTPRINT

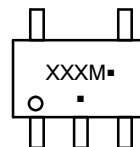
* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.95	1.10
A1	---	---	0.10
A3	0.20 REF		
b	0.10	0.20	0.30
c	0.10	---	0.25
D	1.80	2.00	2.20
E	2.00	2.10	2.20
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.10	0.15	0.30

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:

- PIN 1. BASE
- EMITTER
- BASE
- COLLECTOR
- COLLECTOR

STYLE 2:

- PIN 1. ANODE
- EMITTER
- BASE
- COLLECTOR
- CATHODE

STYLE 3:

- PIN 1. ANODE 1
- N/C
- ANODE 2
- CATHODE 2
- CATHODE 1

STYLE 4:

- PIN 1. SOURCE 1
- DRAIN 1/2
- SOURCE 1
- GATE 1
- GATE 2

STYLE 5:

- PIN 1. CATHODE
- COMMON ANODE
- CATHODE 2
- CATHODE 3
- CATHODE 4

STYLE 6:

- PIN 1. EMITTER 2
- BASE 2
- EMITTER 1
- COLLECTOR
- COLLECTOR 2/BASE 1

STYLE 7:

- PIN 1. BASE
- EMITTER
- BASE
- COLLECTOR
- COLLECTOR

STYLE 8:

- PIN 1. CATHODE
- COLLECTOR
- N/C
- BASE
- EMITTER

STYLE 9:

- PIN 1. ANODE
- CATHODE
- ANODE
- ANODE
- ANODE

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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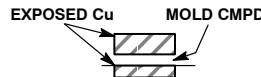
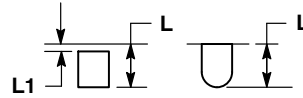
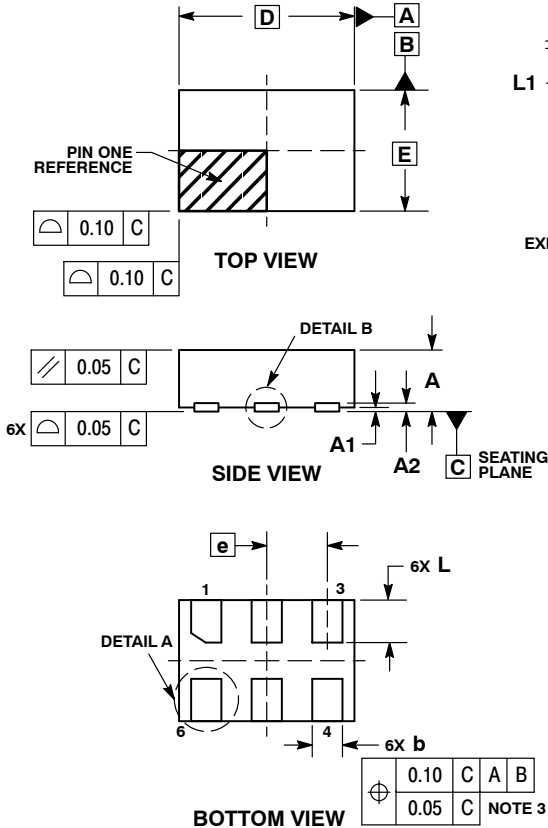
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O

DATE 15 MAY 2008

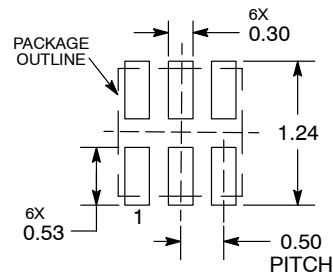


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	UDFN6, 1.45x1.0, 0.5P	PAGE 1 OF 1

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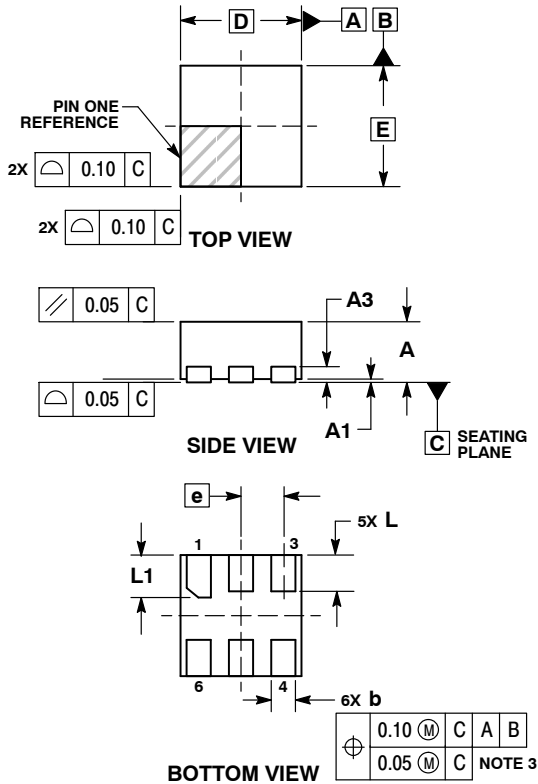
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O

SCALE 4:1

DATE 18 MAY 2011

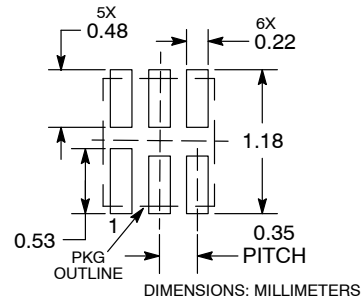


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

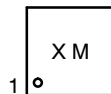
MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.12	0.22
D	1.00	BSC
E	1.00	BSC
e	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

**RECOMMENDED
SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	UDFN6, 1x1, 0.35P	PAGE 1 OF 1

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

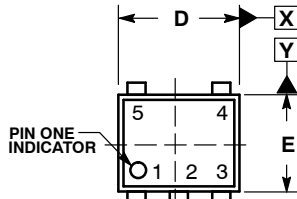
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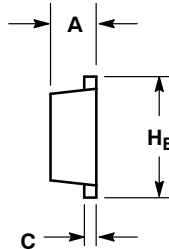
SCALE 4:1

SOT-953
CASE 527AE
ISSUE E

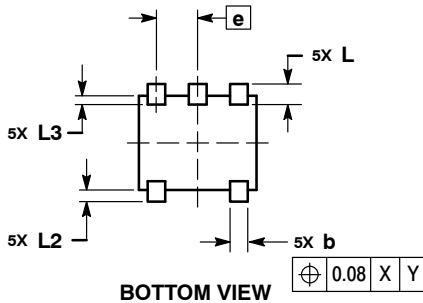
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TOP VIEW



SIDE VIEW



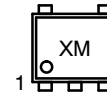
BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35 BSC		
HE	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3	---	---	0.15

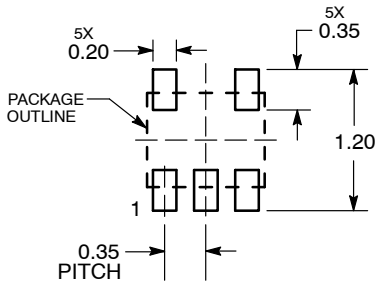
GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOT-953	PAGE 1 OF 1

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